

**CALL FOR PAPERS**  
**IEEE Open Journal of Vehicular Technology (OJVT)**  
**Special Issue on**  
**Emerging Technologies for Modern Electric Vehicles**

With changing consumer habits, government regulations and sustainability requirements, research on electromobility applications, in particular electric vehicles, has drawn much attention. It is anticipated that by 2040, annual sale of electric vehicles is projected to outsell gasoline and diesel vehicles, with estimated sale of 48 million units per year. As one of the most promising electromobility applications, the development of electric vehicles has become a hot research topic. In this area, there are numerous technologies emerging, such as new electric machine topologies, new control algorithms, new power converter designs, sophisticated energy managements, improved manufacturing processes, advanced materials, new energy storages technologies and sources, wireless power transfer technologies, etc. This special issue aims to collect advanced theoretical and technological findings in electric vehicle applications. Manuscripts with both theoretical interpretation and practical verifications are both encouraged. Topics of interest include, but are not limited to:

- Topologies and designs of electric machines
- Control strategies and drives for electric machines
- Topologies and designs of power converters
- Power monitoring and management in electric vehicles
- Manufacturing techniques and infrastructure of electric vehicles
- Electrochemical energy sources for electric vehicles
- Wireless power transfer technologies for electric vehicles

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